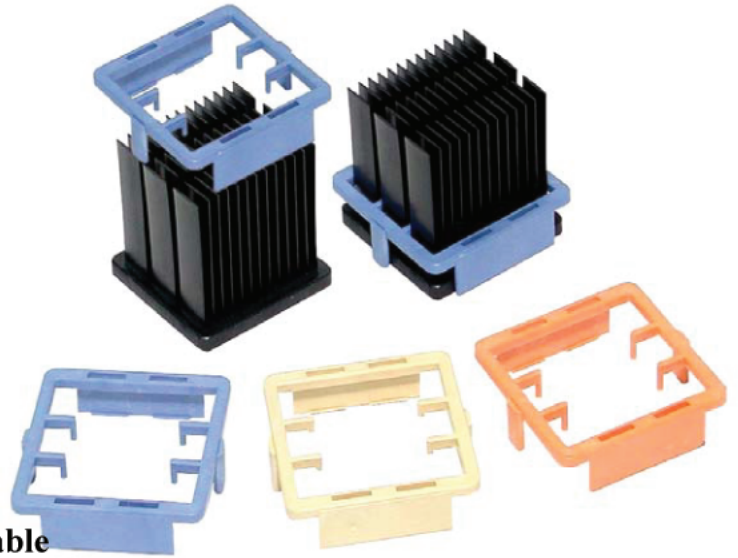


# Model Name : MBA37.5001-23W/2.9

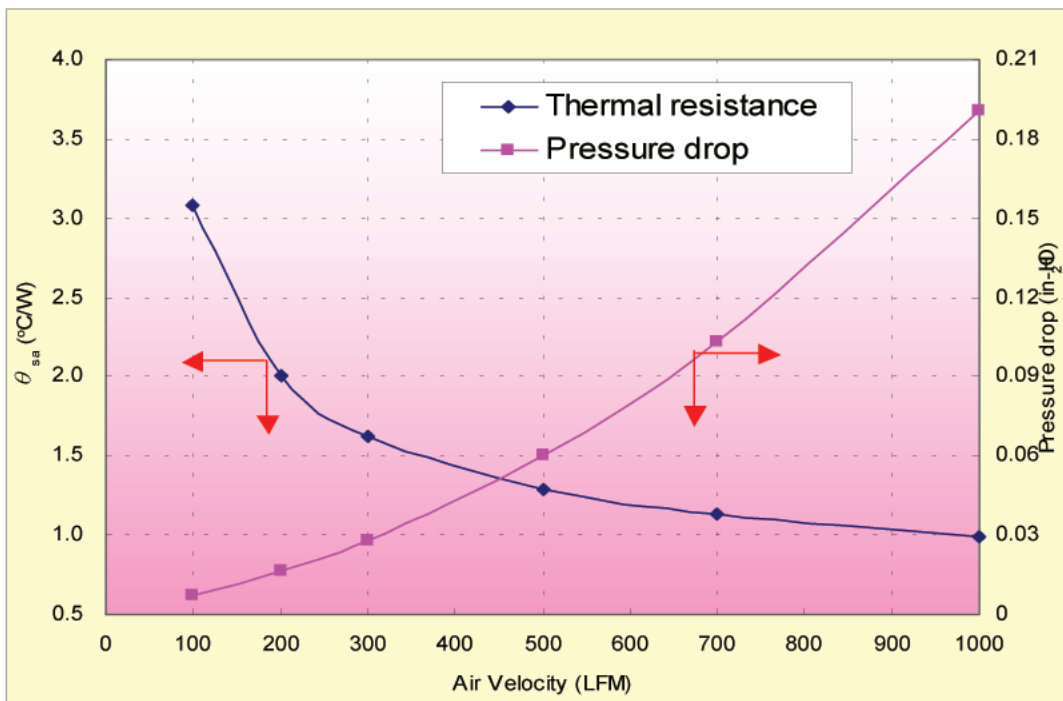
## BGA Heat Sink For 37.5x37.5 Chip set

### Specification:

1. Material:  
Heat Sink : Aluminum 6063  
Clip : Plastic (UL94-V0)
2. Heat Sink Dimension :  
37.5\*37.1\* 22.9 mm height (with base)  
Base : 2.9mm, Fin height : 20mm
3. Available Fin height (without base) :  
12/15/18/20/25/30 mm available
4. Weight: 31 gm
5. Technology: Precision Forging
6. Finish: Black or Nature Anodize
7. For Copper IC package or  
Moulding compound IC package available
8. Heat Source size: Uniform



### Performance Data:



**AMERICAN THERMAL PRODUCTS**

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